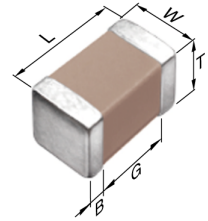


C1608JB1E474M080AC



TDK item description C1608JB1E474MT****

Applications	Commercial Grade
Feature	General General (Up to 50V)
Series	C1608 [EIA 0603]
Status	Production (Not Recommended for New Design)



Dimensions in mm

Size	
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)

Electrical Characteristics	
Capacitance	470nF ±20%
Rated Voltage	25VDC
Temperature Characteristic	JB(±10%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	212MΩ

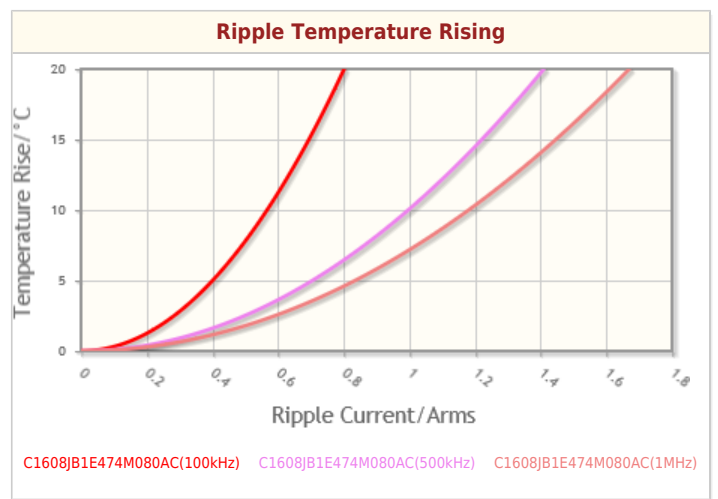
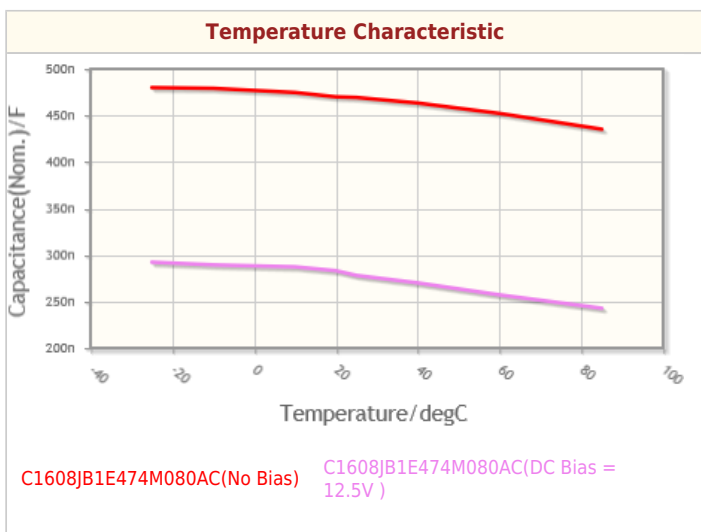
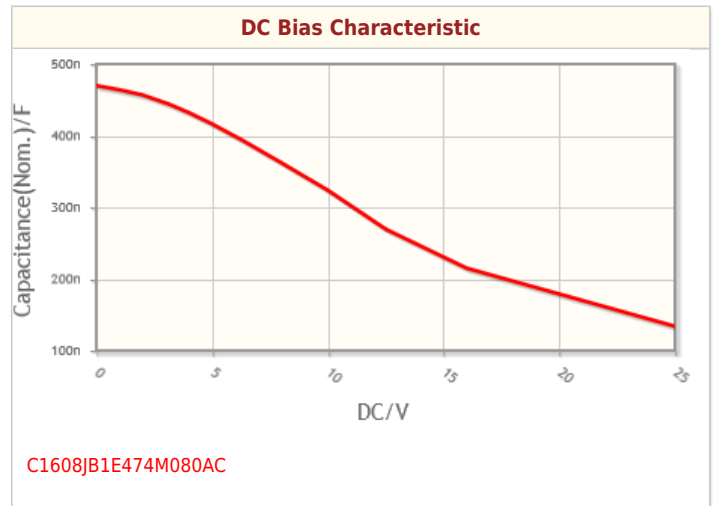
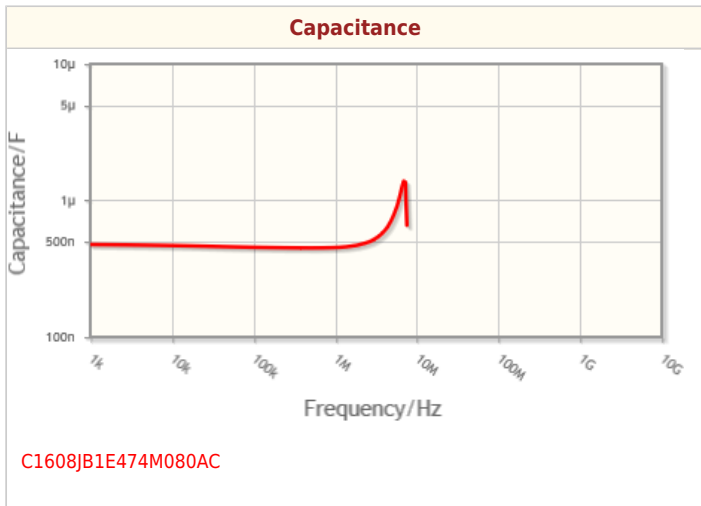
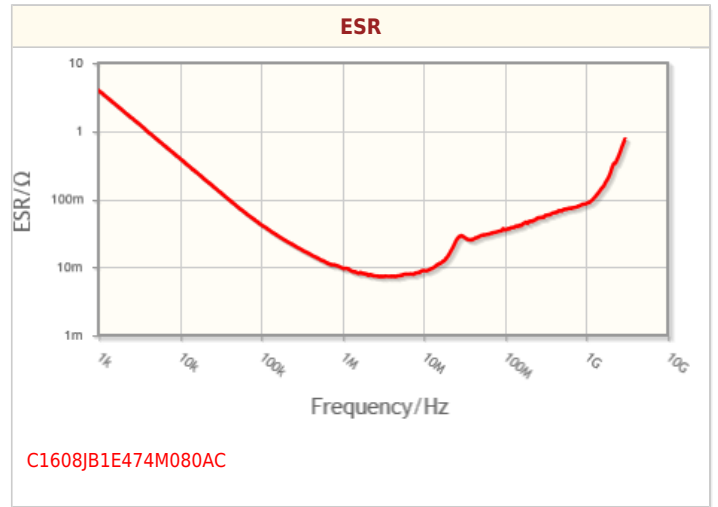
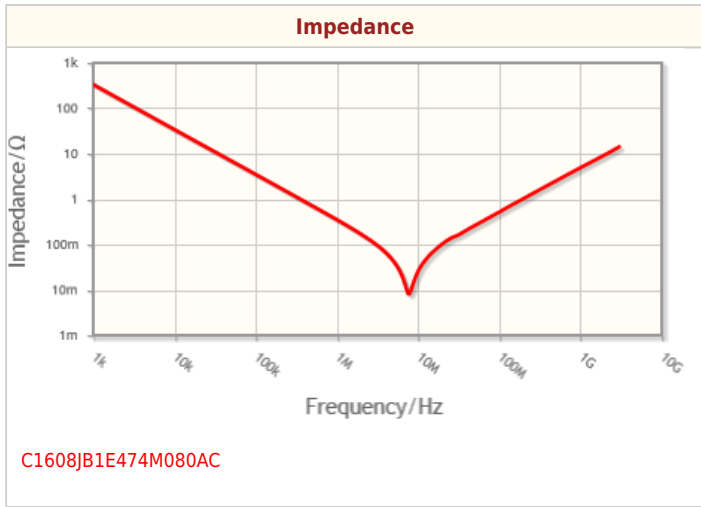
Other	
Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	No
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

! Images are for reference only and show exemplary products.
! This PDF document was created based on the data listed on the TDK Corporation website.
! All specifications are subject to change without notice.

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Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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Associated Images

